

**HLN TECHNOLOGIES LIMITED**  
Registration No. 200402180C

**USE OF SHARE PLACEMENT PROCEEDS**

The Board of Directors of HLN Technologies Limited (the 'Company') refers to the placement of 21,000,000 ordinary shares in the capital of the Company which was completed on 8 September 2008 and wishes to update the use of the placement proceeds as at 15 May 2009.

Amount of placement proceeds raised

	<u>S\$'000</u>
Amount raised	3,129
Less: Placement expenses	<u>(189)</u>
Net placement proceeds	<u>2,940</u>

The actual placement expenses were S\$189,000 compared to the estimated S\$199,000 in the OIS dated 27 August 2008. Hence, approximately S\$10,000 is transferred to working capital purpose of the Group and net placement proceeds increased from S\$2,930,000 to S\$2,940,000.

Use of placement proceeds as at 15 May 2009 is as follows:-

S/N	Intended Use	Amount allocated (S\$'000)	Amount utilized (S\$'000)	Balance amount (S\$'000)
1	To expand the Group's polymeric facility in Suzhou	1,200	1,150	50
2	To repay loans to financial institutions <sup>(1)</sup>	967	967	0
3	As working capital for the Group <sup>(1)</sup>	773	665	108
	<b>Total</b>	<b>2,940</b>	<b>2,782</b>	<b>158</b>

<sup>(1)</sup> The loans to financial institutions have been fully repaid in accordance with the placement, therefore the balance of S\$48,000 has been reallocated to the Group's working capital

The Company will continue to provide regular updates on the use of the balance proceeds.

By order of the Board

Wa Kok Liang  
Chief Executive Officer  
15 May 2009